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***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

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In re application of: BAYAN, et al.

Attorney Docket No.: NSC1P295/P05886

Application No.: New

Filed: Herewith

Title: A DIE ATTACH PAD FOR USE IN  
SEMICONDUCTOR MANUFACTURING AND  
METHOD OF MAKING SAME

**CERTIFICATE OF EXPRESS MAILING**

I hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on February 26, 2004 in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number EV333986859US, addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

  
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Commissioner for Patents  
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Sir:

The undersigned attorney of record in the subject patent application hereby grants an Associate Power of Attorney to Christopher Byrne, Reg. No. 32,204; John Maxin, Reg. No. 34,668; Peter Y. Wang, Reg. No. 40,452; Andrew S. Viger, Reg. No. 28,552; Eugene C. Conser, Reg. No. 39,149; Coleman F. Reif, Reg. No. 38,593; and Allen R. Tremain, Reg. No. 40,207 all of National Semiconductor Corporation to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.


Please send all correspondence for this application as follows:

**Customer Number 022434**

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Respectfully submitted,  
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Date: February 26, 2004